

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC060P03NS3E G	**Issued**	24. January 2018
MA#	MA001809740		
Package	PG-TDSON-8-39	**Weight***	112.97 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.479	2.19	2.19	21946	21946
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.049	0.04		431	
	non noble metal	copper	7440-50-8	48.649	43.08	43.13	430657	431217
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	509	509
encapsulation	organic material	carbon black	1333-86-4	0.081	0.07		720	
	plastics	epoxy resin	-	6.424	5.69		56865	
	inorganic material	silicondioxide	60676-86-0	34.152	30.23	35.99	302319	359904
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13456	13456
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1403	1403
solder	non noble metal	tin	7440-31-5	0.046	0.04		407	
	noble metal	silver	7440-22-4	0.057	0.05		509	
	non noble metal	lead	7439-92-1	2.195	1.94	2.03	19433	20349
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.150	0.13		1328	
	non noble metal	copper	7440-50-8	16.910	14.97	15.12	149693	151216
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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